



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR D<sup>2</sup>PAK, TO-263</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	320	150 000	200 °C + N2	0	0
HAST	1804	180 400	130 °C, 85 % RH	0	0
Power Cycle	492	4 217 424	DELTA T <sub>j</sub> = 100 °C	0	0
Pressure Pot	2824	271 104	121°, 15 PSIG	0	0
Solder DUNK	330	990	260 °C, 10 s	0	0
Solderability	75	1080	883 M2003	0	0
Temp. Cycle	2942	2 762 000	-55 °C to 150 °C	0	0